

**ABSTRACT OF THE DISCLOSURE**

A method and apparatus for attaching an integrated circuit die to a leadframe or substrate. Specifically, a wafer, which is populated with integrated circuit dies, is electrically tested and a wafer map is generated depicting the electrically good dies. An adhesive material is deposited on  
5 only the electrically good dies in accordance with the wafer map. The electrically good integrated circuit die may then be attached to a leadframe or substrate.